

RSJ151P10

Pch 100V 15A Power MOSFET

V_{DSS}	-100V
R _{DS(on)} (Max.)	120m $Ω$
I _D	−15A
P_D	50W

● Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

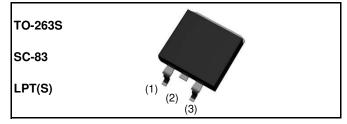
Application

Switching Power Supply

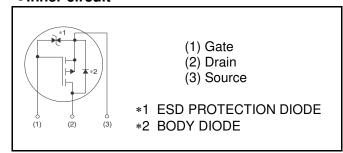
Automotive Motor Drive

Automotive Solenoid Drive

Outline



•Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Type	Tape width (mm)	16
Туре	Basic ordering unit (pcs)	2,500
	Taping code	TL
	Marking	RSJ151P10

•Absolute maximum ratings($T_a = 25$ °C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V_{DSS}	-100	V
Continuous drain current	$T_c = 25^{\circ}C$	I _D *1	±15	А
	T _c = 100°C	I _D *1	±8	А
Pulsed drain current	I _{D,pulse} *2	±30	А	
Gate - Source voltage	V_{GSS}	±20	V	
Avalanche energy, single pulse	E _{AS} *3	33	mJ	
Avalanche current		I _{AR} *3	–15	А
T _c = 25°C		P _D	50	W
Power dissipation $T_a = 25^{\circ}C^{*4}$		P _D	1.35	W
Junction temperature	T _j	150	°C	
Range of storage temperature	T _{stg}	-55 to +150	°C	

●Thermal resistance

Parameter	Symbol	Values			Unit
- Farameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	2.5	°C/W
Thermal resistance, junction - ambient *4	R_{thJA}	-	-	92.6	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

•Electrical characteristics($T_a = 25$ °C)

Parameter	Symbol	Conditions		Values		Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	UTIIL	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = -1mA$	-100	ı	1	V	
		$V_{DS} = -100V, V_{GS} = 0V$			4		
Zoro gata valtaga drain aurrant	1	$T_j = 25^{\circ}C$	-	-	_1	μΑ	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = -100V, V_{GS} = 0V$			-100		
		T _j = 125°C	-	-			
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, \ V_{DS} = 0V$	-	-	±10	μΑ	
Gate threshold voltage	$V_{GS\ (th)}$	$V_{DS} = -10V, I_{D} = -1mA$	-1.0	ı	-2.5	V	
	R _{DS(on)} *5	$V_{GS} = -10V, I_D = -15A$	ı	85	120		
		$V_{GS} = -4.5V, I_D = -15A$	1	95	135		
Static drain - source on - state resistance		$V_{GS} = -4.0V, I_D = -15A$	-	100	140	mΩ	
		$V_{GS} = -10V, I_D = -15A$		- 155	220		
		T _j = 125°C	-		220		
Forward transfer admittance	9 _{fs}	$V_{DS} = -10V, I_{D} = -15A$	13	26	-	S	

• Electrical characteristics ($T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
r arameter	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C _{iss}	$V_{GS} = 0V$	-	3800	-	
Output capacitance	C _{oss}	$V_{DS} = -25V$	-	160	-	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	100	-	
Turn - on delay time	$t_{d(on)}$ *5	$V_{DD} \simeq -50V, V_{GS} = -10V$	-	30	-	
Rise time	t _r *5	$I_D = -7.5A$	-	40	-	no
Turn - off delay time	t _{d(off)} *5	$R_L = 12\Omega$	-	165	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	95	-	

•Gate Charge characteristics($T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
rarameter	Syllibol	ol Conditions -		Тур.	Max.	Offic
Total gate charge	Q_g^{*5}	$V_{DD} \simeq -50V$	-	64	-	
Gate - Source charge	Q_{gs}^{*5}	$I_D = -15A$	-	10	1	nC
Gate - Drain charge	Q_{gd}^{*5}	$V_{GS} = -10V$	-	10	1	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq -50V$, $I_D = -15A$	-	-3.1	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ainietei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Continuous source current	l _S *1	T _c = 25°C	ı	ı	-15	Α
Pulsed source current	I _{SM} *2	1 _c = 25 0	ı	ı	-30	Α
Forward voltage	V_{SD}^{*5}	$V_{GS} = 0V, I_{S} = -15A$	-	-	-1.2	V
Reverse recovery time	t _{rr} *5	I _S = -15A	-	60	-	ns
Reverse recovery charge	Q _{rr} *5	$di/dt = -100A/\mu s$	-	145	-	μС

^{*1} Limited only by maximum temperature allowed.

*5 Pulsed

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L $^{\simeq}$ 200 μ H, V_{DD} = -50V, Rg = 10Ω , starting T_{j} = $25^{\circ}C$

^{*4} Mounted on a epoxy PCB FR4 (20mm × 30mm × 0.8mm)

Fig.1 Power Dissipation Derating Curve

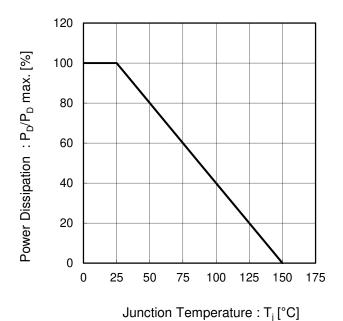
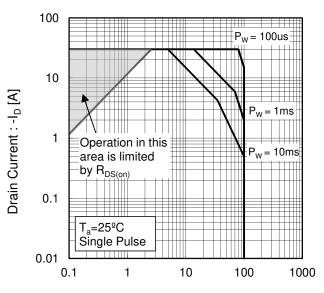
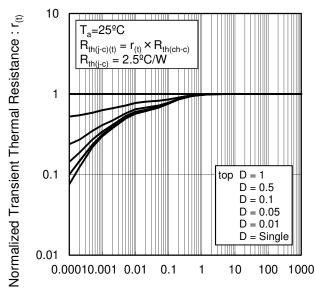


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : -V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width: Pw[s]

Fig.4 Avalanche Current vs Inductive Load

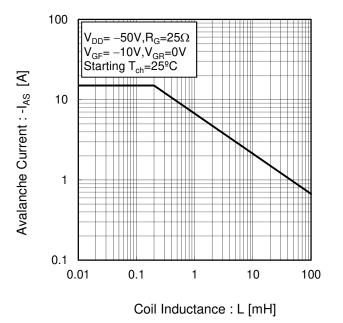
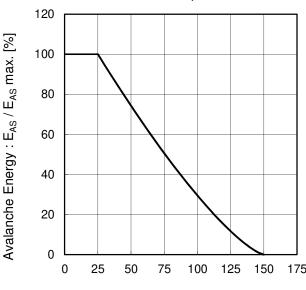
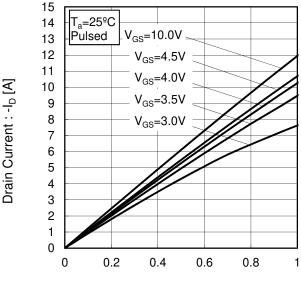


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



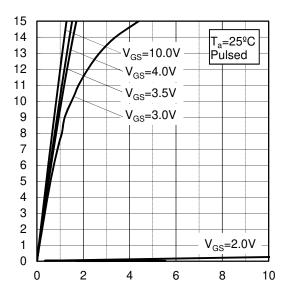
Junction Temperature : T_i [°C]

Fig.6 Typical Output Characteristics(I)



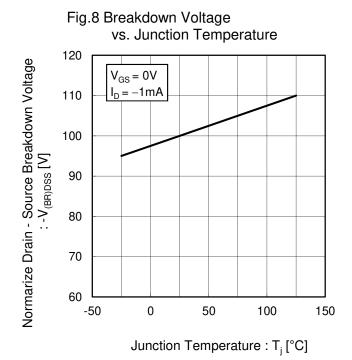
Drain - Source Voltage : -V_{DS} [V]

Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : -V_{DS} [V]

Drain Current : -I_D [A]



100 V_{DS}= -10V 10 V_{DS}= -10V T_a= 125°C T_a= 75°C T_a= 25°C T_a= -25°C

Fig.9 Typical Transfer Characteristics

Gate - Source Voltage : -V_{GS} [V]

Fig.11 Transconductance vs. Drain Current

Fig.10 Gate Threshold Voltage vs. Junction Temperature 3.0 $V_{DS} = -10V$ Gate Threshold Voltage: -VGS(th) [V] 2.5 $I_D = -1 \text{ mA}$ 2.0 1.5 1.0 0.5 0.0 -50 -25 0 25 50 75 100 125 150 Junction Temperature : T_i [°C]

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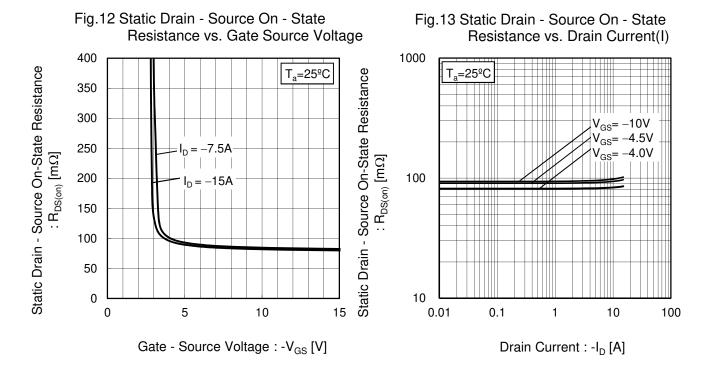
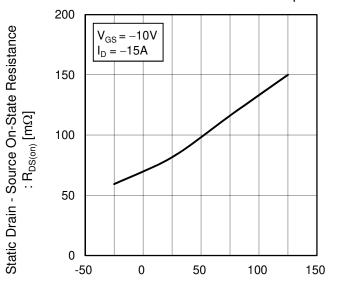


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature



Junction Temperature : T_j [${}^{\circ}C$]

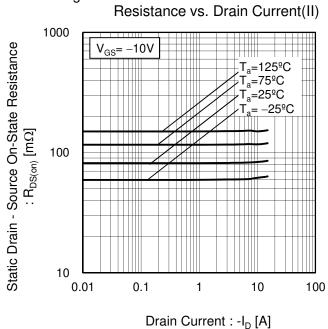


Fig.15 Static Drain - Source On - State

Fig.16 Static Drain - Source On - State
Resistance vs. Drain Current(III)

1000

V_{GS}= -4.5V

T_a=125°C

T_a=75°C

T_a=25°C

T_a=-25°C

Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV) 1000 Static Drain - Source On-State Resistance T_a=125°C _=75ºC =25ºC -25ºC $: R_{DS(on)} [m\Omega]$ 100 10 0.01 0.1 1 10 100 Drain Current : -ID [A]

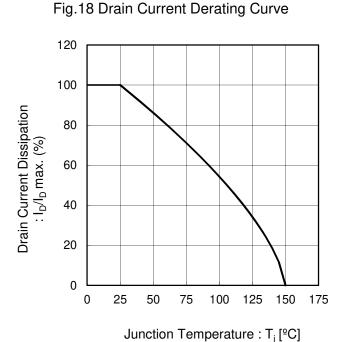
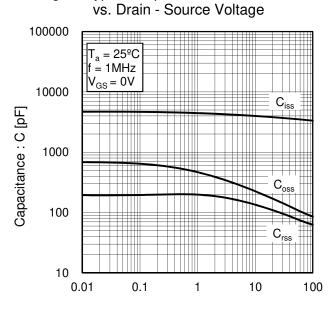
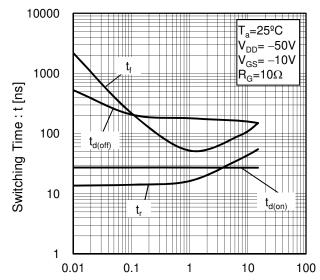


Fig.19 Typical Capacitance



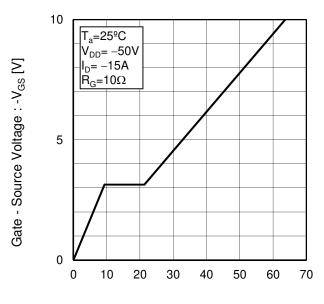
Drain - Source Voltage : $-V_{DS}[V]$

Fig.20 Switching Characteristics



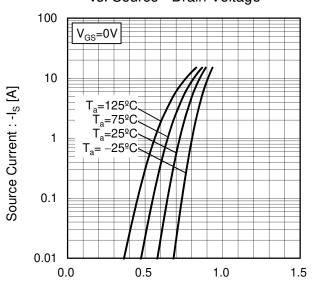
Drain Current : -I_D [A]

Fig.21 Dynamic Input Characteristics

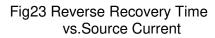


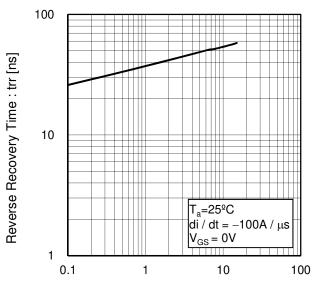
Total Gate Charge : Q_g [nC]

Fig.22 Source Current vs. Source - Drain Voltage



Source-Drain Voltage: -V_{SD}[V]





Source Current : -I_S [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

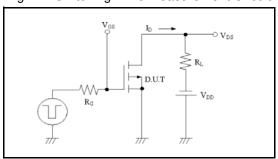


Fig.2-1 Gate Charge Measurement Circuit

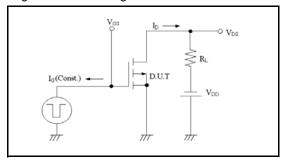


Fig.3-1 Avalanche Measurement Circuit

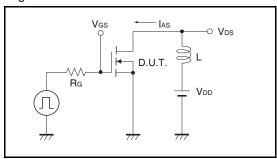


Fig.1-2 Switching Waveforms

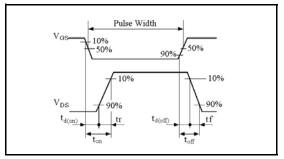


Fig.2-2 Gate Charge Waveform

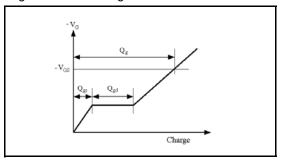
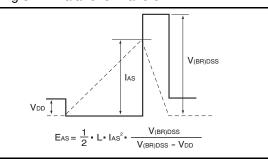
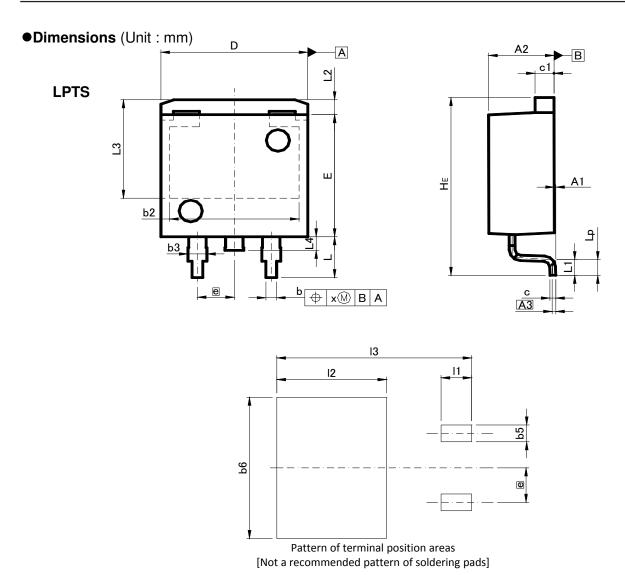


Fig.3-2 Avalanche Waveform





DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.	25	0.0	110
b	0.68	0.98	0.027	0.039
b2	8.	90	0.3	50
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.1	00
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1	0.90	1.50	0.035	0.059
L2	1.	10	0.043	
L3	7.	25	0.285	
L4	1.	00	0.0	139
Lp	0.90	1.50	0.035	0.059
X	_	0.25	_	0.010

1.23 10.40

2.10

7.55 13.40

Dimension in mm / inches

MIN

MILIMETERS

INCHES

MIN

MAX 0.049 0.409

0.083

0.297 0.528

DIM

b5

b6

12 13

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JÁPAN	USA	EU	CHINA
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CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
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